IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	Material Compo © Copyright 2005. IF international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				Materials a	ials and Mfg Information			
upplier Info	rmation				·		·								
Company name*			Company unique ID			τ	Unique ID Authority				Re	Response Date*			
onsemi										20:	2025-05-09				
Contact Name		Title - Contact			1	Phone - Contact*				En	Email - Contact*				
Product-Env-Ste	ewards		Product Enviro Compliance				NA				Pı	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				En	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Pı	Product-Env-Stewards@onsemi.com			
Reque	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date Version Manufacturin		Manufacturing S	Site	Weight*	UOM	Unit Type		
		NTBG080N120SC1 SiC MOS D2PA		SiC MOS D2PAK	K-7L 80mohm 1200V		2025-05-09	)5-09 CPA			1576.704	mg	Each		
Ianufacturin	ng Proccess Informat	ion											·		
Terminal Plating / Grid Array Material T			Ferminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature N		ure Max Time a	t Peak Ten	nperature Num	ber of Reflow Cy	cles			
Matte Tin (Sn) - annealed CU			CU Alloy 1			245 C 30		30		seconds 3					
omments															
vel 1 - maximur	n time at peak temperatu	re during sol	dering is 10-3	30 seconds											
or more inform	ation regarding material o	composition	please refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.29	mg	Supplier	Silicon Carbide	409-21-2		5.29	mg
Die Attach Solder	7.49	mg	Supplier	Silver (Ag)	7440-22-4		0.1873	mg
			A	Lead (Pb)	7439-92-1	7a	6.9282	mg
			Supplier	Tin (Sn)	7440-31-5		0.3745	mg
Lead Frame	921.0	mg	В	Nickel (Ni)	7440-02-0		9.21	mg
			Supplier	Copper (Cu)	7440-50-8		911.79	mg
Mold Compound-Black	626.0			Epoxy resin	proprietary data		18.78	mg
			Supplier	Phenolic Resin	Proprietary Data		9.39	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		93.9	mg
			Supplier	Carbon Black (C)	1333-86-4		3.13	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		500.8	mg
Plating	0.224	mg	Supplier	Tin (Sn)	7440-31-5		0.224	mg
Wire Bond - Al	16.7	mg	Supplier	Aluminum (Al)	7429-90-5		16.7	mg